Record Nr. UNINA9910791454203321 Lead-free solder interconnect reliability [[electronic resource] /] / **Titolo** edited by Dongkai Shangguan Pubbl/distr/stampa Materials Park, OH, : ASM International, 2005 **ISBN** 1-61503-093-X Descrizione fisica 1 online resource (302 p.) Altri autori (Persone) ShangguanDongkai <1963-> Disciplina 621.381/046 Soggetti Microelectronic packaging - Reliability Solder and soldering Lead-free electronics manufacturing processes Lingua di pubblicazione Inglese **Formato** Materiale a stampa Livello bibliografico Monografia Note generali Description based upon print version of record. Nota di bibliografia Includes bibliographical references and index. ""Contents""; ""Foreword""; ""Preface""; ""Lead-Free Soldering and Nota di contenuto Environmental Compliance: An Overview"; ""Microstructural Evolution and Interfacial Interactions in Lead-Free Solder Interconnects"; ""Fatigue and Creep of Lead-Free Solder Allovs: Fundamental Properties""; ""Lead-Free Solder Joint Reliability Trends""; ""Chemical Interactions and Reliability Testing for Lead-Free Solder Interconnects""; ""Tin Whisker Growth on Lead-Free Solder Finishes""; ""Accelerated Testing Methodology for Lead-Free Solder Interconnects"" ""Thermomechanical Reliability Prediction of Lead-Free Solder Interconnects"""Design for Reliability Finite Element Modeling of Lead-Free Solder Interconnects""; ""Characterization and Failure Analyses of Lead-Free Solder Defects""; ""Reliability of Interconnects with Conductive Adhesives""; ""Lead-Free Solder Interconnect Reliability Outlook""; ""Index""